

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number: [73644-1003](#)
Status: **Active**
Overview: [HDM® Backplane Connector System](#)
Description: HDM® Board-to-Board Backplane Header, Vertical, SMC, Press-Fit, Guide Post Location A, Polarizing Key Position B, 144 Circuits

Documents:

[3D Model](#) [RoHS Certificate of Compliance \(PDF\)](#)
[Drawing \(PDF\)](#)

Agency Certification

CSA LR19980
 UL E29179

General

Product Family Backplane Connectors
 Series [73644](#)
 Application Backplane
 Comments Standard Press-Fit
 Component Type PCB Header
 Overview [HDM® Backplane Connector System](#)
 Product Name HDM®
 UPC 800755023008

Physical

Circuits (Loaded) 144
 Circuits (maximum) 144
 Color - Resin Black, Natural
 Durability (mating cycles max) 250
 First Mate / Last Break No
 Flammability 94V-0
 Guide to Mating Part Yes
 Keying to Mating Part Yes
 Material - Metal Phosphor Bronze, Stainless Steel
 Material - Plating Mating Gold
 Material - Plating Termination Gold
 Material - Resin High Temperature Thermoplastic
 Number of Columns 24
 Number of Pairs Open Pin Field
 Number of Rows 6
 Orientation Vertical
 PC Tail Length 3.50mm
 PCB Locator No
 PCB Retention Yes
 PCB Thickness - Recommended 2.50mm
 Packaging Type Tube
 Pitch - Mating Interface 2.00mm
 Pitch - Termination Interface 2.00mm
 Plating min - Mating 0.762µm
 Plating min - Termination 0.051µm
 Polarized to PCB No
 Stackable Yes
 Surface Mount Compatible (SMC) Yes
 Temperature Range - Operating -55°C to +105°C
 Termination Interface: Style Through Hole - Compliant Pin



image - Reference only

EU RoHS

ELV and RoHS Compliant
REACH SVHC Not Reviewed
Low-Halogen Status Not Reviewed

China RoHS



Need more information on product environmental compliance?

Email productcompliance@molex.com
 For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series

[73644Series](#)

Mates With

73632 HDM PLUS® Board-to-Board Daughtercard Receptacle. 73780 HDM® Board-to-Board Daughtercard Receptacle

Application Tooling | FAQ

Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Global

Description	Product #
Extraction Tool	0621001000
Backplane Insertion	0621001400
Signal Contact Tool	
Backplane Insertion	0622005703
Head for 144 Circuits	

Electrical

Current - Maximum per Contact	1.0A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	75
Shielded	No
Voltage - Maximum	250V AC

Material Info**Reference - Drawing Numbers**

Sales Drawing	SDA-73644-****
---------------	----------------

HDM and High Density Metric are trademarks of Amphenol Corporation

This document was generated on 04/28/2015

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION